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N-Channel IGBT 600V, 20A, VCE(sat);1.45V TO-3PF-3L with Low VF Switching Diode

Features

- IGBT V_{CE}(sat)=1.45V typ. (I_C=20A, V_{GE}=15V)
- IGBT t_f=67ns typ.
- Diode $V_F=1.5V$ typ. ($I_F=20A$)
- Diode t_{rr}=70ns typ.

- Adaption of full isolation type package
- Enhansment type
- Maxium junction temperature Tj=175°C

Applications

• Power factor correction of white goods appliance

• General purpose inverter

Specifications

Absolute Maximum Ratings at Ta = 25°C, Unless otherwise specified

Parameter	Symbol	Conditions		Ratings	Unit		
Collector to Emitter Voltage	VCES					600	>
Gate to Emitter Voltage	VGES			±20	٧		
Collector Current (DC)	1 +4	Limited by Tjmax	@ Tc=25°C *2	40	Α		
	IC*1		@ Tc=100°C *2	20	Α		
Collector Current (Pulse)	ICP	Pulse width Limited by Tjmax		80	Α		
Diode Average Output Current	Ю			20	Α		
Allowable Power Dissipation	PD	Tc=25°C (Our ideal heat dissipation condition) *2		64	W		

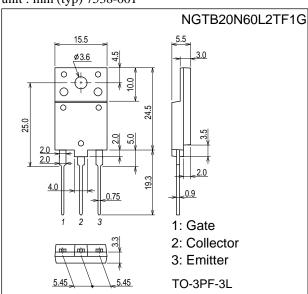
Note: *1 Collector Current is calculated from the following formula.

 $I_{C}(\text{Tc}) = \frac{\text{Tjmax - Tc}}{R_{\text{th}}(j\text{-c}) \times V_{CE}(\text{sat})(\text{Tjmax, }I_{C}(\text{Tc}))}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Package Dimensions

unit: mm (typ) 7538-001



Ordering & Package Information

Device	Package	Shipping	note
NGTB20N60L2TF1G	TO-3PF-3L SC-94	30 pcs. / tube	Pb-Free

Marking

© © © © GTB20N © 60L2: LOT No.

Electrical Connection

Continued on next page.

^{*2} Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminium.

Continued from preceding page.

Parameter	Symbol	Conditions	Ratings	Unit
Junction Temperature	Tj		175	°C
Storage Temperature	Tstg		- 55 to +175	°C

Electrical Characteristics at Ta = 25°C, Unless otherwise specified

Parameter	Cumbal	Conditions		Ratings		Unit
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to Emitter Breakdown Voltage	V(BR)CES	I _C =500μA, V _{GE} =0V	600			V
0.11	ICES	V _{CE} =600V, V _{GE} =0V T _c =25°C T _c =150°C	С		10	μΑ
Collector to Emitter Cut off Current			С		1	mA
Gate to Emitter Leakage Current	IGES	V _{GE} =±20V, V _{CE} =0V			±100	nA
Gate to Emitter Threshold Voltage	V _{GE} (th)	V _{CE} =20V, I _C =250μA	4.5		6.5	V
Collector to Emitter Seturation Valters	\/a= ()	V _{GE} =15V, I _C =20A T _c =25°	С	1.45	1.65	V
Collector to Emitter Saturation Voltage	VCE (sat)	Tc=150°	С	1.8		V
Diode Forward Voltage	VF	I _F =20A		1.5		V
Input Capacitance	Cies			2000		pF
Output Capacitance	Coes	V _{CE} =20V,f=1MHz		60		pF
Reverse Transfer Capacitance	Cres			50		pF
Turn-ON Delay Time	t _d (on)	V _{CC} =300V,I _C =20A R _G =30Ω,L=200μH V _{GE} =0V/15V, Vclamp=400V See Fig.1, Fig.2		60		ns
Rise Time	t _r			37		ns
Turn-ON Time	ton			400		ns
Turn-OFF Delay Time	t _d (off)			193		ns
Fall Time	tf			67		ns
Turn-OFF Time	toff			281		ns
Total Gate Charge	Qg	V _{CE} =300V, V _{GE} =15V, I _C =20A		84		nC
Gate to Emitter Charge	Qge			16		nC
Gate to Collector "Miller" Charge	Qgc			37		nC
Diode Reverse Recovery Time	t _{rr}	I _F =10A , di/dt=100A/μs, V _{CC} =50V See Fig	J.3	70		ns

Thermal Characteristics at Ta = 25°C, Unless otherwise specified

Parameter	Symbol	Conditions	Ratings	Unit
Thermal Resistance IGBT (junction- case)	Rth(j-c)(IGBT)	Tc=25°C (our ideal heat dissipation condition)*2	2.33	°C /W
Thermal Resistance Diode (junction- case)	Rth(j-c)(Diode)	Tc=25°C (our ideal heat dissipation condition)*2	2.36	°C /W
Thermal Resistance (junction- atmosphere)	Rth(j-a)		47.5	°C /W

Fig.1 Switching Time Test Circuit

Clamp Di

OOO
200µH

DUT

VCC

Fig.2 Timing Chart

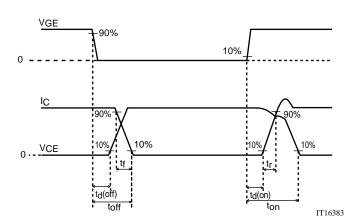
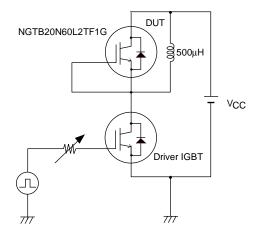
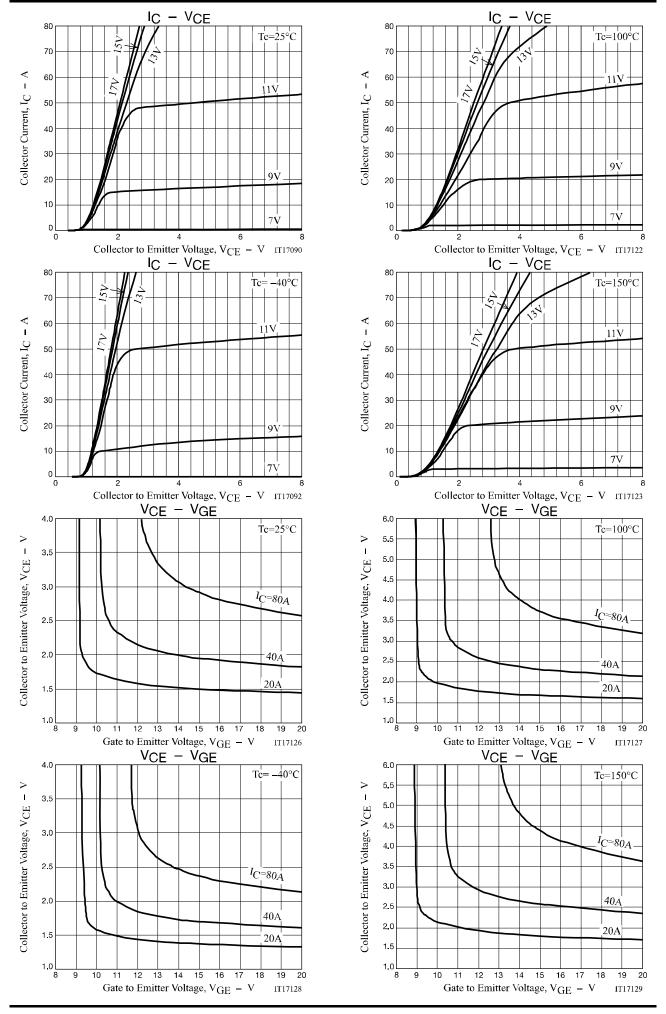
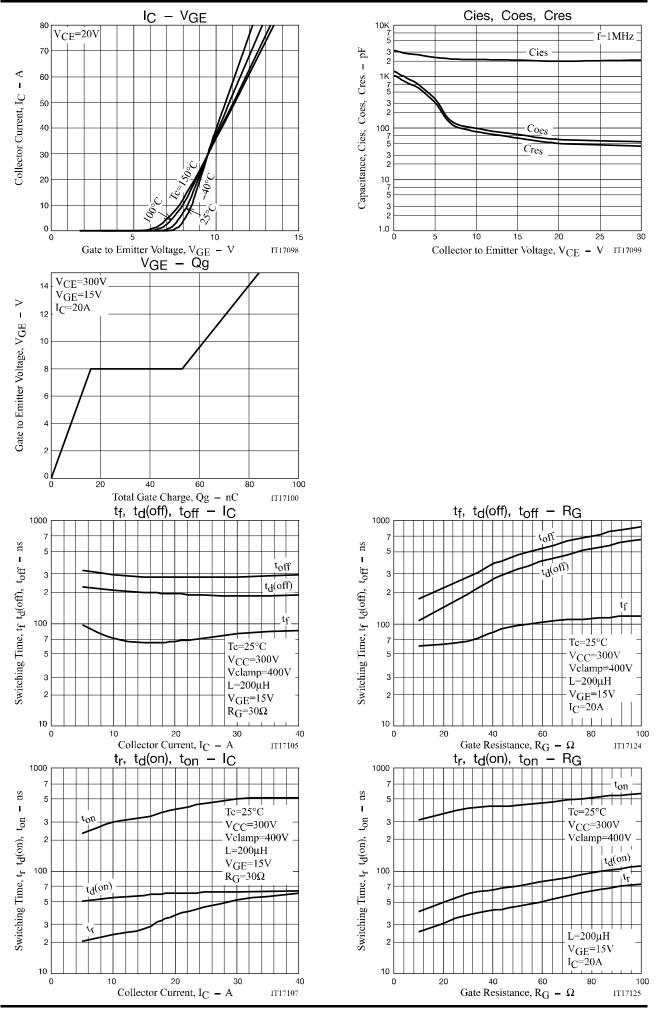
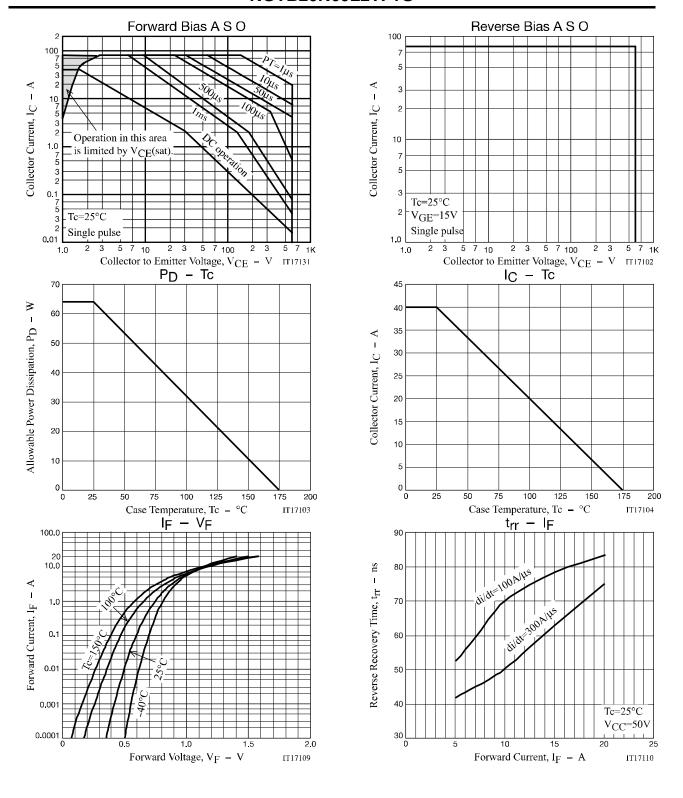


Fig.3 Reverse Recovery Time Test Circuit



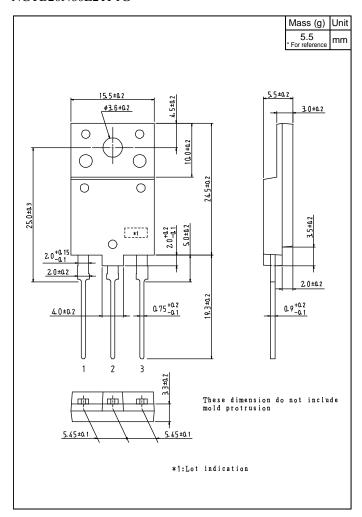






Outline Drawing

NGTB20N60L2TF1G



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